

CLAIMS:

- Subcl
- 5 1. A system comprising at least two printed circuit boards on which printed circuits are provided, said printed circuit boards each comprising electrical contact elements for electrically interconnecting the printed circuit boards, characterized in that the electrical contact elements of one printed circuit board are formed by a number of electroconductive pins manufactured so as to be in one piece with said printed circuit board, and in that the electrical contact elements of the other printed circuit board are formed by a number of recesses having an electroconductive inner surface formed in said other printed circuit board, the pins entering the corresponding recesses and being secured therein by soldering.
- 10 2. A system as claimed in claim 1, wherein the electroconductive pins are coated on all sides with an electroconductive material, in particular a metal.
- 15 3. A system as claimed in claim 1 or 2, wherein the inner surface of the recesses is coated on all sides with an electroconductive material, in particular a metal.
- 20 4. A system as claimed in claim 2 or 3, wherein the electroconductive material is provided by means of electrolysis.
- 5 5. A system as claimed in claim 2, 3 or 4, wherein the thickness of the electroconductive material ranges between 25 μm and 40 μm , and is in particular approximately 35 μm .
- 25 6. A system as claimed in any one of the preceding claims 1 through 5, wherein the electroconductive pins have a diameter below 3 mm, in particular below 2 mm, and more in particular below 1.5 mm.
7. A method of manufacturing printed circuit boards which are part of a system as claimed in any one of the preceding claims 1 through 6, wherein the electroconductive

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pins are formed by material removal, in particular milling or drilling, from one printed circuit board.

8. A method as claimed in claim 7, wherein adjoining electroconductive pins of one printed circuit board are electrically insulated with respect to each other by removing intermediate material from said printed circuit board, in particular by means of milling or drilling.

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